

MULTI-CHIP MODULE WITH BUILT-IN ELECTRONIC PART

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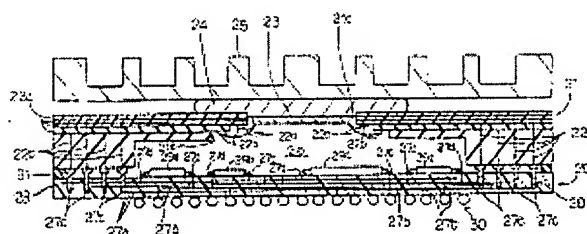
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Multi-layer wiring structures are respectively formed in upper and lower ceramic substrates for electric parts, and interconnecting pins held in contact with contact pads establish electrical connections between the multi-layer wiring structures so as to prevent a multi-chip module from an undesirable disconnection between the multi-layer wiring structures.



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